

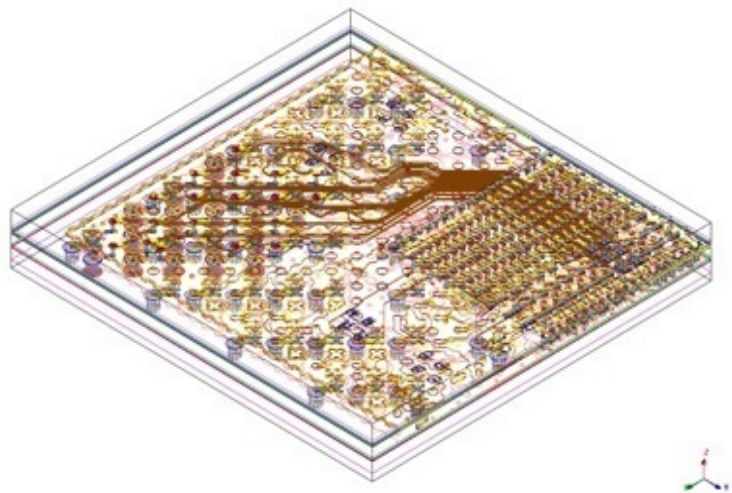


Workshop - 3D Layout Simulation Platform for EDA Design Flow Automation

Introduction

As a complement to the traditional arbitrary 3D CAD-based modeling interface, the HFSS 3D Layout interface is a significant productivity enhancement for IC Package and PCB designers. HFSS 3D Layout allows engineers to easily create fully parametric models and perform design studies of printed circuit boards (PCB), electronic packages, and custom integrated circuits.

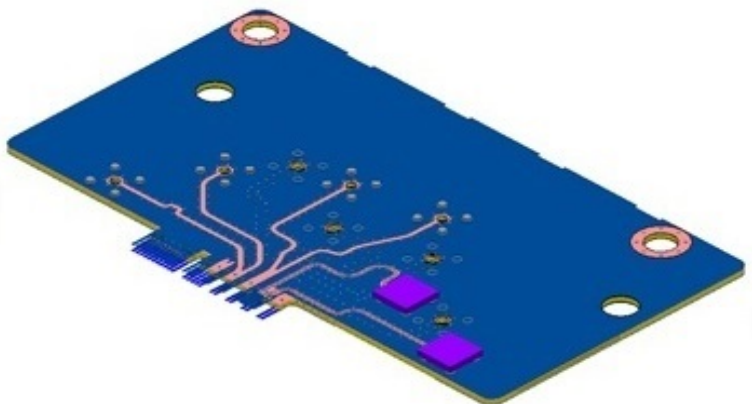
During this workshop both package and PCB examples will be used to highlight the functionality and automation provided by HFSS and how to improve performance and productivity. In addition, the built-in parametric interface enables design engineers to explore design alternatives and evaluate design trade-offs prior to fabrication. Complementing the engineering efficiency, a set of advanced technologies will be presented that enable faster HFSS simulations through the application of high-performance computing (HPC).



Objectives

This half-day workshop demonstrates the fully automated 3D electrical layout interface enabled in ANSYS HFSS 15. There will be product briefing and feature update for ANSYS HFSS 3D Layout. Each topic is followed by "hands-on" workshops and exercises. Attendees will be able to learn the following:-

- ANSYS HFSS 3D Layout workflow for layered structure simulation
- New user interface and design platform for 3D electrical layout problems
- Parametric study in HFSS 3D Layout for design exploration



Who Should Attend

- Signal integrity (SI) / power integrity (PI) engineers and managers who need to conduct or understand SI/PI simulation with 3D electrical layout design

- RF / antenna engineers and managers who need to design RF circuits and antennas on PCB or IC packages
- Electronics packaging and PCB designers who are taking care of electrical performance of design layout

About the speaker



Dr. Zheng Boyu joined CAD-IT as a Technical Consultant in 2013, after working as team leader and R&D engineer in various organisations such as Institute of Microelectronics (A*STAR Singapore), United Test and Assembly Centre, EPCOS, and Huawei. He holds a Ph.D. from Nanyang Technological University, Singapore.

Boyu has a strong background in RF/Microwave, wireless, and microelectronics with more than 13 years' experience in the research and development of RF circuits, antennas, and high-speed systems including design and electrical modeling, optimisation, prototype development and testing. In the past 6 years he has been in microelectronic industry focusing on advanced packaging development and electrical performance sign-off.

Workshop Information

Dates : 5th September 2014 (Friday)
Time : 2:00 pm - 5:30 pm
Venue : CAD-IT Consultants (Asia) Pte Ltd
 159 Sin Ming Road, #03-05, Amtech Building, Singapore 575625 ([view map](#))

Agenda	1:30pm - 2:00pm	Registration
	2:00pm - 2:40pm	Introduction to ANSYS HFSS 3D Layout
	2:40pm - 3:20pm	Hands-on exercise on BGA package simulation
	3:20pm - 3:50pm	Tea break
	3:50pm - 4:30pm	Hands-on exercise on PCIe Gen3 PCB simulation
	4:30pm - 4:50pm	Example on parametric study in ANSYS HFSS 3D Layout
	4:50am - 5:30pm	Hands-on exercise on planar filter design

Register NOW

- Register online for this FREE one-off workshop.
- Seats are limited and allocated on a first-come-first-serve basis. So please book your place early to avoid disappointment.
- CAD-IT Consultants reserves the right to cancel or postpone the event due to unforeseen circumstances.

For enquiries, please call 6508-7575 or email at caditevents@cadit.com.sg

About CAD-IT Consultants

Founded in 1991, CAD-IT is a leading global ISO 9001:2008 certified Product Life Cycle Management (PLM), manufacturing and education provider. CAD-IT's mission is to provide world-class solutions and services that enable companies and their supply chains to achieve greater product innovation, quality and productivity with drastically reduced time-to-market and costs.

CAD-IT is honored to have received over 80 international and national awards since its inception for marketing and service excellence. Among its most recent accolades are the Singapore Enterprise 50 Award (2013, 2012), Singapore SME 1000 (2014, 2013, 2012, 2011), Asia Pacific Entrepreneur Award (APEA) - Outstanding Entrepreneur Award (2012, 2010, 2009), the Singapore Prestige Brand Award SPBA - Established Brand Award (2012, 2011, 2010, 2009), SPBA - Regional Brand Award 2012 and SPBA -

Hall of Fame 2012.

CAD-IT Consultants' suite of PLM solutions include ANSYS (System-level, Multiphysics Simulation), Goldfire Innovator (Innovation Process Management), Moldflow (Plastics CAE), Stampack (Sheet Metal Forming), Deform (Bulk Metal Forming CAE), SpaceClaim (3D Direct Modeler), Mentor Graphics Valor DFM (Design For Manufacturing), Valor MSS (Complete Manufacturing Execution Suite) and Cortona3D (3D Technical Documentation).

Since February 2010, CAD-IT has partnered the Singapore Workforce Development Agency (WDA) to offer Advanced Certificate courses in PLM and Engineering Simulation, under the Workforce Skills Qualifications (WSQ) framework, with the charter to upgrade the technological capabilities of organizations in Singapore so as to enable them to undertake high value-add design, engineering, manufacturing and R&D activities.



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